

Title (en)
PACKAGED DEVICE

Title (de)
VERKAPSELTE ANORDNUNG

Title (fr)
DISPOSITIF ENCAPSULE

Publication
EP 1068499 A1 20010117 (EN)

Application
EP 00902715 A 20000203

Priority

- GB 0000298 W 20000203
- GB 9902341 A 19990203
- GB 0002433 A 20000203

Abstract (en)
[origin: WO0046580A1] A transducer has a closure for components mounted on the substrate (13) comprising: a lid component (16); and a peripheral component (17) of plastics material secured by one side to the lid component (16) and by the other side to the one side to the substrate (13); the lid component (16) and the peripheral component (17) serve to define a hermetically sealed enclosure (18) for the electrode structure (12). The invention further comprises a workpiece bearing the transducer to enable strain generated in the workpiece to be examined by way of the transducer.

IPC 1-7
G01L 1/16

IPC 8 full level
H01L 23/02 (2006.01); **H03H 3/08** (2006.01); **H03H 9/10** (2006.01); **H03H 9/25** (2006.01)

CPC (source: EP)
H03H 9/1071 (2013.01)

Citation (search report)
See references of WO 0046580A1

Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)
WO 0046580 A1 20000810; AU 2446000 A 20000825; BR 0004588 A 20020205; CA 2326981 A1 20000810; CN 1300362 A 20010620; EP 1068499 A1 20010117; JP 2002536894 A 20021029

DOCDB simple family (application)
GB 0000298 W 20000203; AU 2446000 A 20000203; BR 0004588 A 20000203; CA 2326981 A 20000203; CN 00800489 A 20000203; EP 00902715 A 20000203; JP 2000597613 A 20000203